

Appln No. 10/043,763

Amdt date August 5, 2004

Reply to Office action of June 7, 2004

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Canceled)

2. (Previously Presented) A method of protecting an integrated circuit from over voltage, the method comprising:

accepting a voltage from a power supply input to the integrated circuit;

accepting a pad voltage from an external voltage source;

comparing the power supply voltage to a predetermined value;

coupling a bias voltage for the integrated circuit to a gate of a PMOS (P-channel Metal Oxide Semiconductor) device when the power supply is below the predetermined value; and

coupling the pad voltage to a bias_mid node through the PMOS device to provide the bias voltage for the integrated circuit when the power supply is below the predetermined value,

wherein coupling the bias voltage for the integrated circuit to the gate of the PMOS (P-channel Metal Oxide Semiconductor) device when the power supply is below the predetermined value comprises coupling the bias voltage to the gate of the PMOS (P-channel Metal Oxide Semiconductor) device through a first plurality of diode connected MOS devices when the power supply is below the predetermined value.

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3. (Canceled)

4. (Previously Presented) A method of protecting an integrated circuit from over voltage, the method comprising:

accepting a voltage from a power supply input to the integrated circuit;

accepting a pad voltage from an external voltage source;

comparing the power supply voltage to a predetermined value;

coupling a bias voltage for the integrated circuit to a gate of a PMOS (P-channel Metal Oxide Semiconductor) device when the power supply is below the predetermined value; and

providing the pad voltage to an input of a plurality of diode connected MOS devices; and

coupling an output of the plurality of diode connected MOS devices to the drain of the PMOS device to couple the pad voltage to a bias_mid node to provide the bias voltage for the integrated circuit when the power supply is below the predetermined value.

Claims 5-22 (Canceled)

23. (Previously Presented) A method for generating a bias voltage (bias_mid) from a pad voltage (Vpad), when a power supply (V_{DDO}) is not present the method comprising:

providing V_{DDO} to a gate of a first semiconductor device;

providing bias_mid to a source of the first semiconductor device such that the first semiconductor device will turn off when $V_{DDO} - \text{bias_mid}$ is less than the threshold of the first semiconductor device; and

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providing bias_mid to a gate of a MOS device in response to the turn off of the first semiconductor device to turn on the MOS device to couple Vpad to bias_mid,

wherein providing bias_mid to the gate of the MOS device in response to the turn off of the first semiconductor device to turn on the MOS device to couple Vpad to bias_mid comprises:

turning on a second semiconductor device and turning off a third semiconductor device which is coupled to the second semiconductor device thereby providing bias_mid to the gate of the MOS device to turn on the MOS device; and

using the turn on of the MOS device to couple Vpad to bias_mid, and

wherein using the turn on of the MOS device to couple Vpad to bias_mid comprises:

providing the pad voltage to an input of a first plurality of diode connected MOS devices; and

coupling an output of the first plurality of diode connected MOS devices to the drain of the MOS device.

24. (Previously Presented) A method for generating a bias voltage (bias_mid) from a pad voltage (Vpad), when a power supply (V_{DD0}) is not present the method comprising:

providing V_{DD0} to a gate of a first semiconductor device;

providing bias_mid to a source of the first semiconductor device such that the first semiconductor device will turn off when $V_{DD0} - \text{bias_mid}$ is less than the threshold of the first semiconductor device; and

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providing bias_{mid} to a gate of a MOS device in response to the turn off of the first semiconductor device to turn on the MOS device to couple V_{pad} to bias_{mid},

wherein providing bias_{mid} to the gate of the MOS device comprises providing bias_{mid} to the gate of the MOS device through a second plurality of diode connected MOS devices in response to the turn off of the first semiconductor device.

25. (Previously Presented) A method for generating a bias voltage (bias_{mid}) from a pad voltage (V_{pad}), when a power supply (V_{DDO}) is not present the method comprising:

providing V_{DDO} to a gate of a first semiconductor device;

providing bias_{mid} to a source of the first semiconductor device such that the first semiconductor device will turn off when V_{DDO} - bias_{mid} is less than the threshold of the first semiconductor device; and

providing bias_{mid} to a gate of a MOS device in response to the turn off of the first semiconductor device to turn on the MOS device to couple V_{pad} to bias_{mid},

wherein providing bias_{mid} to the gate of the MOS device in response to the turn off of the first semiconductor device to turn on the MOS device to couple V_{pad} to bias_{mid} comprises:

turning on a second semiconductor device and turning off a third semiconductor device which is coupled to the second semiconductor device thereby providing bias_{mid} to the gate of the MOS device to turn on the MOS device; and

using the turn on of the MOS device to couple V_{pad} to bias_{mid}, and

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wherein turning on a second semiconductor device and turning off a third semiconductor device comprises turning on a second semiconductor device, coupling Vpad to a gate of the third semiconductor device through a third plurality of diode connected MOS devices and the second semiconductor device to turn off the third semiconductor device.

26. (Previously Presented) The method of claim 4 further comprising:

providing V_{DDO} to a gate of a first semiconductor device

providing the bias voltage for the integrated circuit to a source of the first semiconductor device such that the first semiconductor device will turn off when V_{DDO} minus the bias voltage for the integrated circuit is less than the threshold of the first semiconductor device; and

providing the bias voltage for the integrated circuit to the PMOS (P-channel Metal Oxide Semiconductor) device in response to the turn off of the first semiconductor device to couple the pad voltage to a bias_mid node to provide the bias voltage for the integrated circuit when the power supply is below the predetermined value.

27. (Previously Presented) The method of claim 4 wherein providing the bias voltage for the integrated circuit to the gate of the PMOS (P-channel Metal Oxide Semiconductor) device in response to the turn off of the first semiconductor device to couple the pad voltage to a bias_mid node comprises:

turning on a second semiconductor device and turning off a third semiconductor device which is coupled to the second

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semiconductor device thereby providing the bias voltage for the integrated circuit to the gate of the PMOS (P-channel Metal Oxide Semiconductor) device to turn on the PMOS (P-channel Metal Oxide Semiconductor) device; and

using the turn on of the PMOS (P-channel Metal Oxide Semiconductor) device to couple the pad voltage to a bias_mid node comprises.

28. (Previously Presented) The method of claim 4 wherein providing the bias voltage for the integrated circuit to the gate of the PMOS (P-channel Metal Oxide Semiconductor) device comprises providing the bias voltage for the integrated circuit to the gate of the PMOS (P-channel Metal Oxide Semiconductor) through a second plurality of diode connected MOS devices in response to the turn off of the first semiconductor device.

29. (Previously Presented) The method of claim 27 wherein turning on a second semiconductor device and turning off a third semiconductor device comprises turning on a second semiconductor device, coupling the bias voltage for the integrated circuit to a gate of the third semiconductor device through a third plurality of diode connected MOS devices and the second semiconductor device to turn off the third semiconductor device.

30. (Canceled)

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31. (Currently Amended) ~~The method of claim 30,~~ A method of protecting an integrated circuit from over voltage, the method comprising:

accepting a voltage from a power supply input to the integrated circuit;

accepting a pad voltage via a pad from an external voltage source to the integrated circuit; and

if the power supply voltage has a first value less than a predetermined value:

turning off a first switch disposed between the pad and a gate terminal of a second switch disposed between the pad and a bias node; and

turning on a third switch disposed between the bias node and the gate terminal of the second switch,

thereby turning on the second switch to provide a bias voltage for the integrated circuit at the bias node;

wherein the pad voltage is applied at the bias node as the bias voltage through a plurality of diode connected transistors and the second switch.

32. (Currently Amended) ~~The method of claim 30,~~ A method of protecting an integrated circuit from over voltage, the method comprising:

accepting a voltage from a power supply input to the integrated circuit;

accepting a pad voltage via a pad from an external voltage source to the integrated circuit; and

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if the power supply voltage has a first value less than a predetermined value:

turning off a first switch disposed between the pad and a gate terminal of a second switch disposed between the pad and a bias node; and

turning on a third switch disposed between the bias node and the gate terminal of the second switch,

thereby turning on the second switch to provide a bias voltage for the integrated circuit at the bias node;

wherein said turning off the first switch comprises applying the pad voltage at a gate terminal of the first switch through a plurality of diode connected transistors.

33. (Previously Presented) The method of claim 32, wherein said applying the pad voltage comprises turning on a fourth switch disposed between the gate terminal of the first switch and the pad voltage.

34. (Currently Amended) ~~The method of claim 30,~~ A method of protecting an integrated circuit from over voltage, the method comprising:

accepting a voltage from a power supply input to the integrated circuit;

accepting a pad voltage via a pad from an external voltage source to the integrated circuit; and

if the power supply voltage has a first value less than a predetermined value:

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turning off a first switch disposed between the pad and a gate terminal of a second switch disposed between the pad and a bias node; and

turning on a third switch disposed between the bias node and the gate terminal of the second switch,

thereby turning on the second switch to provide a bias voltage for the integrated circuit at the bias node;

wherein the third switch is coupled to the gate terminal of the second switch through a plurality of diode connected transistors.

35. (Currently Amended) The method of ~~claim 30~~claim 31, further comprising:

if the power supply voltage has a second value greater than the predetermined value, turning off the second switch, such that the pad voltage is not provided to the bias node through the second switch.